

# 6A, 200V - 1000V Standard Surface Mount Rectifier

#### **FEATURES**

- AEC-Q101 qualified
- Glass passivated chip junction
- High surge current capability
- Ideal for automated placement
- Wettable flank
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

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- DC to DC converter
- Automotive application
- Car lighting
- Snubber

### **MECHANICAL DATA**

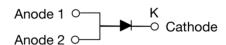
- Case: TO-277A (SMPC4.6U)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.107g (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
I <sub>F</sub>	6	Α		
$V_{RRM}$	200 - 1000	V		
I <sub>FSM</sub>	140	Α		
$T_{JMAX}$	150	°C		
Package	TO-277A (SMPC4.6U)			
Configuration	Single die			





TO-277A (SMPC4.6U)



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)								
PARAMETER		SYMBOL	TUAS 6DH	TUAS 6GH	TUAS 6JH	TUAS 6KH	TUAS 6MH	UNIT
Marking code on the dev	Marking code on the device		AS6D	AS6G	AS6J	AS6K	AS6M	
Repetitive peak reverse voltage		$V_{RRM}$	200	400	600	800	1000	V
Reverse voltage, total rms value		V <sub>R(RMS)</sub>	140	280	420	560	700	V
Forward current		I <sub>F</sub>	6				Α	
Surge peak forward current single half sinewave superimposed on rated load $t = 8.3 \text{ms}$ $t = 1.0 \text{ms}$					140			- A
		I <sub>FSM</sub>			300			
Junction temperature		T <sub>J</sub>	-55 to +150				°C	
Storage temperature		T <sub>STG</sub>	-55 to +150				°C	

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THERMAL PERFORMANCE					
PARAMETER	SYMBOL	TYP	UNIT		
Junction-to-lead thermal resistance	$R_{\Theta JL}$	5	°C/W		
Junction-to-ambient thermal resistance	R <sub>OJA</sub>	45	°C/W		
Junction-to-case thermal resistance	R <sub>eJC</sub>	7.9	°C/W		

Thermal Performance Note: Units mounted on PCB (16mm x 16mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)						
PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage <sup>(1)</sup>		I <sub>F</sub> = 3A, T <sub>J</sub> = 25°C	V <sub>F</sub>	0.91	-	V
		I <sub>F</sub> = 6A, T <sub>J</sub> = 25°C		0.98	1.10	V
		I <sub>F</sub> = 3A, T <sub>J</sub> = 125°C		0.80	-	V
				0.88	-	V
Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>		T <sub>J</sub> = 25°C	I <sub>R</sub>	-	5	μΑ
		T <sub>J</sub> = 125°C		13	-	μΑ
TUAS6DH TUAS6GH Junction capacitance TUAS6JH		1MHz, V <sub>R</sub> = 4.0V	C <sub>J</sub>	43	-	pF
	TUAS6KH TUAS6MH			39	-	

### Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION					
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING			
TUAS6xH	TO-277A (SMPC4.6U)	6,000 / Tape & Reel			

## Notes:

1. "x" define voltage from 200V(TUAS6DH) to 1000V(TUAS6MH)



### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

**Fig.1 Forward Current Derating Curve** 

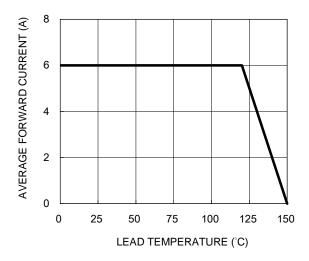
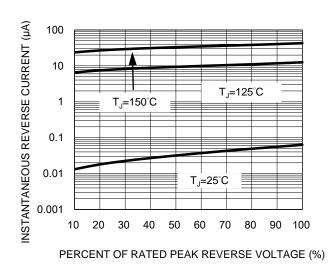


Fig.3 Typical Reverse Characteristics



**Fig.2 Typical Junction Capacitance** 

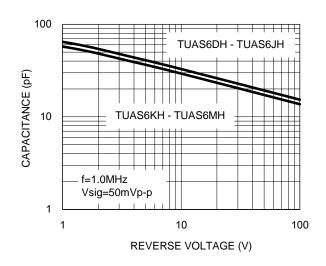


Fig.4 Typical Forward Characteristics

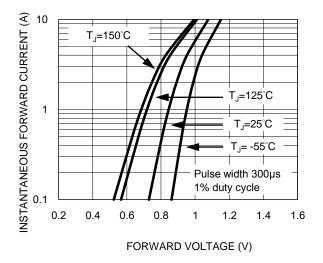
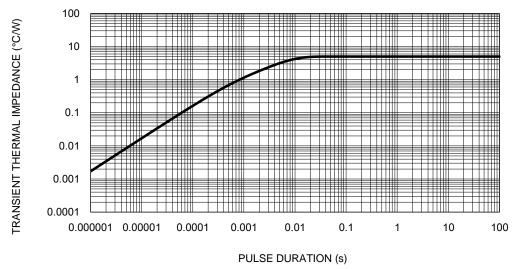


Fig.5 Typical Transient Thermal Impedance

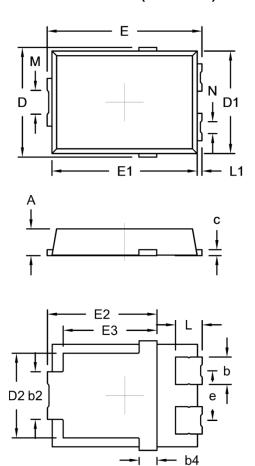


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# **PACKAGE OUTLINE DIMENSIONS**

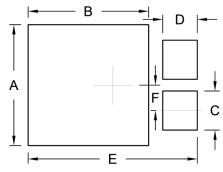
### TO-277A (SMPC4.6U)



DIM.	Unit	(mm)	Unit (inch)		
DIIVI.	Min.	Max.	Min.	Max.	
Α	1.00	1.20	0.039	0.047	
b	1.05	1.35	0.041	0.053	
b2	1.90	2.20	0.075	0.087	
b4	0.75 (	NOM.)	0.030	(NOM.)	
С	0.15	0.40	0.006	0.016	
D	4.45	4.75	0.175	0.187	
D1	4.25	4.35	0.167	0.171	
D2	3.40	3.70	0.134	0.146	
E	6.35	6.65	0.250	0.262	
E1	6.05	6.15	0.238	0.242	
E2	4.40	4.80	0.173	0.189	
E3	3.94 (NOM.)		0.155 (NOM.)		
е	2.08 (NOM.)		0.082 (NOM.)		
L	0.94	1.24	0.037	0.049	
L1	0.05	0.35	0.002	0.014	
М	0.65	1.15	0.026	0.045	
N	0.25	0.75	0.010	0.030	

Package body size D1 and E1 do not include mold flash Mold flash shall not exceed 0.1mm per side

# **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	4.95	0.195
В	4.95	0.195
С	1.60	0.063
D	1.42	0.056
E	6.95	0.274
F	1.04	0.041

This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met.

### **MARKING DIAGRAM**



= Marking Code P/N YW = Date Code F = Factory Code

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